



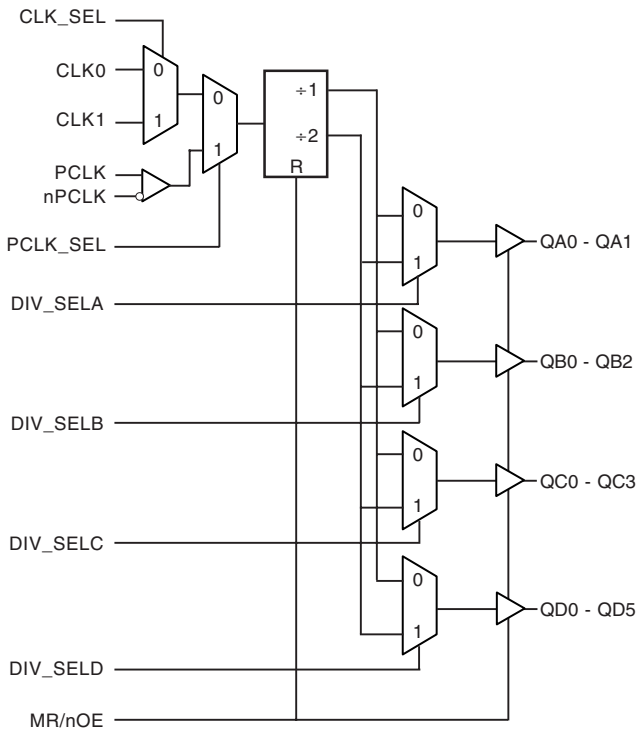
GENERAL DESCRIPTION

The ICS87949-01 is a low skew, ÷1, ÷2 Clock Generator and a member of the HiPerClockS™ family of High Performance Clock Solutions from ICS. The ICS87949-01 has selectable single ended clock or LVPECL clock inputs. The single ended clock input accepts LVCMOS or LVTTTL input levels. The PCLK, nPCLK pair can accept LVPECL, CML, or SSTL input levels. The low impedance LVCMOS outputs are designed to drive 50Ω series or parallel terminated transmission lines. The effective fanout can be increased from 15 to 30 by utilizing the ability of the outputs to drive two series terminated lines.

The divide select inputs, DIV_SELx, control the output frequency of each bank. The outputs can be utilized in the ÷1, ÷2 or a combination of ÷1 and ÷2 modes. The master reset input, MR/nOE, resets the internal frequency dividers and also controls the active and high impedance states of all outputs.

The ICS87949-01 is characterized at 3.3V core/3.3V output and 3.3V core/ 2.5V output. Guaranteed bank, output and part-to-part skew characteristics make the ICS87949-01 ideal for those clock distribution applications demanding well defined performance and repeatability.

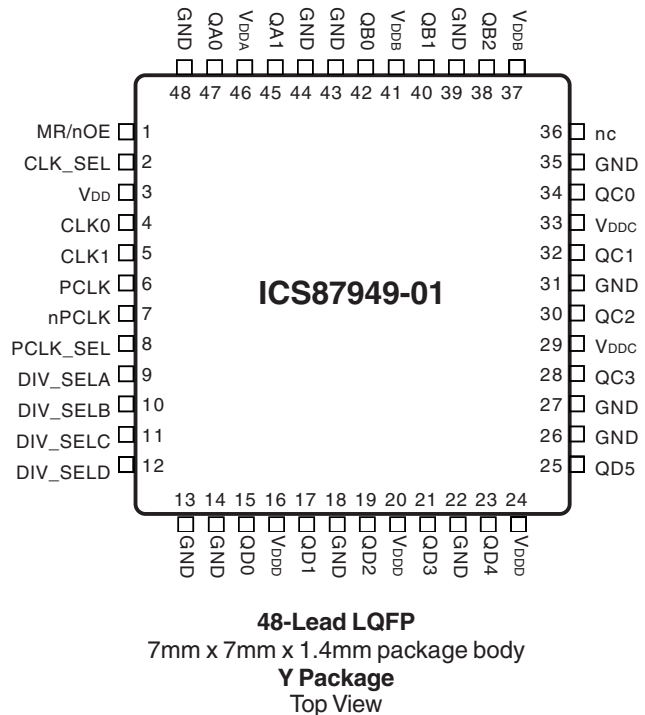
BLOCK DIAGRAM



FEATURES

- 15 single ended LVCMOS outputs, 7Ω typical output impedance
- Selectable LVCMOS or LVPECL clock inputs
- CLK0 and CLK1 can accept the following input levels: LVCMOS and LVTTTL
- PCLK, nPCLK supports the following input types: LVPECL, CML, SSTL
- Maximum input frequency: 250MHz
- Output skew: 200ps (maximum)
- Part-to-part skew: 500ps (typical)
- Multiple frequency skew: 350ps (maximum)
- 3.3V input, outputs may be either 3.3V or 2.5V supply modes
- 0°C to 70°C ambient operating temperature
- Industrial temperature information available upon request
- Functionally compatible to the MPC949 in a smaller footprint requiring less board space

PIN ASSIGNMENT



The Preliminary Information presented herein represents a product in prototyping or pre-production. The noted characteristics are based on initial product characterization. Integrated Circuit Systems, Incorporated (ICS) reserves the right to change any circuitry or specifications without notice.



TABLE 1. PIN DESCRIPTIONS

Number	Name	Type		Description
1	MR/nOE	Input	Pulldown	Master reset and output enable. Resets outputs to tristate. Enables and disables all outputs. LVCMOS interface levels.
2	CLK_SEL	Input	Pulldown	Clock select input. When HIGH, selects CLK1. When LOW, selects CLK0. LVCMOS / LVTTTL interface levels.
3	V _{DD}	Power		Positive supply pin. Connect to 3.3V.
4, 5	CLK0, CLK1	Input	Pullup	LVCMOS / LVTTTL clock inputs.
6	PCLK	Input	Pulldown	Non-inverting differential LVPECL clock input.
7	nPCLK	Input	Pullup	Inverting differential LVPECL clock input.
8	PCLK_SEL	Input	Pulldown	PCLK select input.
9	DIV_SELA	Input	Pulldown	Controls frequency division for Bank A outputs. LVCMOS interface levels.
10	DIV_SELB	Input	Pulldown	Controls frequency division for Bank B outputs. LVCMOS interface levels.
11	DIV_SELC	Input	Pulldown	Controls frequency division for Bank C outputs. LVCMOS interface levels.
12	DIV_SELD	Input	Pulldown	Controls frequency division for Bank D outputs. LVCMOS interface levels.
13, 14, 18, 22, 26, 27, 31, 35, 39, 43, 44, 48	GND	Power		Power supply ground. Connect to ground.
15, 17, 19, 21, 23, 25	QD0, QD1, QD2, QD3, QD4, QD5	Output		Bank D outputs. LVCMOS interface levels. 7Ω typical output impedance.
16, 20, 24,	V _{DDD}	Power		Positive supply pins for Bank D outputs. Connect to 3.3V or 2.5V.
28, 30, 32, 34	QC3, QC2, QC1, QC0	Output		Bank C outputs. LVCMOS interface levels. 7Ω typical output impedance.
29, 33	V _{DDC}	Power		Positive supply pins for Bank C outputs. Connect to 3.3V or 2.5V.
36	nc	Unused		No connect.
37, 41	V _{ddb}	Power		Positive supply pins for Bank B outputs. Connect to 3.3V or 2.5V.
38, 40, 42	QB2, QB1, QB0	Output		Bank B outputs. LVCMOS interface levels. 7Ω typical output impedance.
45, 47	QA1, QA0	Output		Bank A outputs. LVCMOS interface levels. 7Ω typical output impedance.
46	V _{DDA}	Power		Positive supply pins for Bank A outputs. Connect to 3.3V or 2.5V.

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.



TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C_{IN}	Input Capacitance				4	pF
R_{PULLUP}	Input Pullup Resistor			51		$K\Omega$
$R_{PULLDOWN}$	Input Pulldown Resistor			51		$K\Omega$
C_{PD}	Power Dissipation Capacitance (per output)	$V_{DD}, *V_{DDx} = 3.465V$		TBD		pF
R_{OUT}	Output Impedance			7		Ω

*NOTE: V_{DDx} denotes $V_{DDA}, V_{DDB}, V_{DDC}, V_{DD}$.

TABLE 3. FUNCTION TABLE

Inputs					Outputs			
MR/nOE	DIV_SELA	DIV_SELB	DIV_SELC	DIV SELD	QA0 - QA1	QB0 - QB2	QC0 - QC3	QD0 - QD5
1	X	X	X	X	Hi Z	Hi Z	Hi Z	Hi Z
0	0	X	X	X	fIN/1	Active	Active	Active
0	1	X	X	X	fIN/2	Active	Active	Active
0	X	0	X	X	Active	fIN/1	Active	Active
0	X	1	X	X	Active	fIN/2	Active	Active
0	X	X	0	X	Active	Active	fIN/1	Active
0	X	X	1	X	Active	Active	fIN/2	Active
0	X	X	X	0	Active	Active	Active	fIN/1
0	X	X	X	1	Active	Active	Active	fIN/2



ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{DDx}	4.6V
Inputs, V_I	-0.5V to $V_{DD} + 0.5V$
Outputs, V_O	-0.5V to $V_{DD} + 0.5V$
Package Thermal Impedance, θ_{JA}	47.9°C/W (0 lfpm)
Storage Temperature, T_{STG}	-65°C to 150°C

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

TABLE 4A. POWER SUPPLY DC CHARACTERISTICS, $V_{DD} = V_{DDx} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Positive Supply Voltage		3.135	3.3	3.465	V
* V_{DDx}	Output Supply Voltage		3.135	3.3	3.465	V
I_{DD}	Core Supply Current			50		mA
** I_{DDx}	Output Supply Current			14		mA

* V_{DDx} denotes V_{DDA} , V_{DDB} , V_{DDC} , V_{DDD} .

** I_{DDx} denotes I_{DDA} , I_{ddb} , I_{DDC} , I_{DDD} .

TABLE 4B. LVCMOS DC CHARACTERISTICS, $V_{DD} = V_{DDx} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage	DIV_SELA, DIV_SELB, DIV_SELC, DIV_SELD, CLK_SEL, PCLK_SEL, MR/nOE	2		$V_{DD} + 0.3$	V
		CLK0, CLK1	2		$V_{DD} + 0.3$	V
V_{IL}	Input Low Voltage	DIV_SELA, DIV_SELB, DIV_SELC, DIV_SELD, CLK_SEL, PCLK_SEL, MR/nOE	-0.3		0.8	V
		CLK0, CLK1	-0.3		1.3	V
I_{IH}	Input High Current	DIV_SELA, DIV_SELB, DIV_SELC, DIV_SELD, CLK_SEL, PCLK_SEL, MR/nOE	* $V_{DDx} = V_{IN} = 3.465V$		150	μA
		CLK0, CLK1	* $V_{DDx} = V_{IN} = 3.465V$		5	μA
I_{IL}	Input Low Current	DIV_SELA, DIV_SELB, DIV_SELC, DIV_SELD, CLK_SEL, PCLK_SEL, MR/nOE	* $V_{DDx} = 3.465V, V_{IN} = 0V$	-5		μA
		CLK0, CLK1	* $V_{DDx} = 3.465V, V_{IN} = 0V$	-150		μA
V_{OH}	Output High Voltage; NOTE 1		2.6			V
V_{OL}	Output Low Voltage; NOTE 1				0.5	V
I_{OZL}	Output Tristate Current Low				TBD	V
I_{OZH}	Output Tristate Current High				TBD	V

NOTE 1: Outputs terminated with 50Ω to $V_{DDx}/2$. See page 8, Figure 1A, 3.3V Output Load Test Circuit.

*NOTE: V_{DDx} denotes V_{DD} , V_{DDA} , V_{DDB} , V_{DDC} , V_{DDD} .



TABLE 4C. LVPECL DC CHARACTERISTICS, $V_{DD} = V_{DDx} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
I_{IH}	Input High Current	PCLK	$*V_{DDx} = V_{IN} = 3.465V$		150	μA
		nPCLK	$*V_{DDx} = V_{IN} = 3.465V$		5	μA
I_{IL}	Input Low Current	PCLK	$*V_{DDx} = 3.465V, V_{IN} = 0V$	-5		μA
		nPCLK	$*V_{DDx} = 3.465V, V_{IN} = 0V$	-150		μA
V_{PP}	Peak-to-Peak Input Voltage		0.3		1	V
V_{CMR}	Common Mode Input Voltage; NOTE 1, 2		GND + 1.5		V_{DD}	V

NOTE 1: Common mode voltage is defined as V_{IH} .

NOTE 2: For single ended applications, the maximum input voltage for PCLK and nPCLK is $V_{DD} + 0.3V$.

NOTE: $*V_{DDx}$ denotes $V_{DD}, V_{DDA}, V_{DDB}, V_{DDC}, V_{DDD}$.

TABLE 5A. AC CHARACTERISTICS, $V_{DD} = V_{DDx} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{MAX}	Input Frequency				250	MHz
tp_{LH}	Propagation Delay, Low to High; NOTE 1	$f \leq 250MHz$		3.5		ns
tp_{HL}	Propagation Delay, High to Low; NOTE 1	$f \leq 250MHz$		3.5		ns
$tsk(b)$	Bank Skew; NOTE 2, 7	Measured on rising edge at $V_{DDx}/2$			100	ps
$tsk(o)$	Output Skew; NOTE 3, 7	Measured on rising edge at $V_{DDx}/2$			200	ps
$tsk(w)$	Multiple Frequency Skew; NOTE 4, 7	Measured on rising edge at $V_{DDx}/2$			350	ps
$tsk(pp)$	Part-to-Part Skew; NOTE 5, 7	Measured on rising edge at $V_{DDx}/2$		500		ps
t_R	Output Rise Time; NOTE 6	20% to 80%		700		ps
t_F	Output Fall Time; NOTE 6	20% to 80%		700		ps
odc	Output Duty Cycle			50		%
t_{EN}	Output Enable Time; NOTE 6	$f = 10MHz$				ns
t_{DIS}	Output Disable Time; NOTE 6	$f = 10MHz$				ns

All parameters measured at 250MHz unless noted otherwise.

NOTE 1: Measured from the $V_{DD}/2$ of the input to $V_{DDx}/2$ of the output.

NOTE 2: Defined as skew within a bank of outputs at the same supply voltages and with equal load conditions.

NOTE 3: Defined as skew across banks of outputs at the same supply voltages and with equal load conditions.

Measured at $V_{DDx}/2$.

NOTE 4: Defined as skew across banks of outputs operating at different frequencies with the same supply voltages and equal load conditions.

NOTE 5: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at $V_{DDx}/2$.

NOTE 6: These parameters are guaranteed by characterization. Not tested in production.

NOTE 7: This parameter is defined in accordance with JEDEC Standard 65.



TABLE 4D. POWER SUPPLY DC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$, $V_{DDx} = 2.5V \pm 5\%$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Positive Supply Voltage		3.135	3.3	3.465	V
$*V_{DDx}$	Output Supply Voltage		2.375	2.5	2.625	V
I_{DD}	Core Supply Current			50		mA
$**I_{DDx}$	Output Supply Current			13		mA

$*V_{DDx}$ denotes V_{DDA} , V_{DDB} , V_{DDC} , V_{DDD} .

$**I_{DDx}$ denotes I_{DDA} , I_{DDB} , I_{DDC} , I_{DDD} .

TABLE 4E. LVCMOS DC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$, $V_{DDx} = 2.5V \pm 5\%$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage	DIV_SELA, DIV_SELB, DIV_SELC, DIV_SELD, CLK_SEL, PCLK_SEL, MR/nOE	2		$V_{DD} + 0.3$	V
		CLK0, CLK1	2		$V_{DD} + 0.3$	V
V_{IL}	Input Low Voltage	DIV_SELA, DIV_SELB, DIV_SELC, DIV_SELD, CLK_SEL, PCLK_SEL, MR/nOE	-0.3		0.8	V
		CLK0, CLK1	-0.3		1.3	V
I_{IH}	Input High Current	DIV_SELA, DIV_SELB, DIV_SELC, DIV_SELD, CLK_SEL, PCLK_SEL, MR/nOE $V_{DD} = V_{IN} = 3.465V$			150	μA
		CLK0, CLK1 $V_{DD} = V_{IN} = 3.465V$			5	μA
I_{IL}	Input Low Current	DIV_SELA, DIV_SELB, DIV_SELC, DIV_SELD, CLK_SEL, PCLK_SEL, MR/nOE $V_{DD} = 3.465V, V_{IN} = 0V$	-5			μA
		CLK0, CLK1 $V_{DD} = 3.465V, V_{IN} = 0V$	-150			μA
V_{OH}	Output High Voltage; NOTE 1		1.8			V
V_{OL}	Output Low Voltage; NOTE 1				0.5	V
I_{OZL}	Output Tristate Current Low				TBD	V
I_{OZH}	Output Tristate Current High				TBD	V

NOTE 1: Outputs terminated with 50Ω to $V_{DDx}/2$. See page 8, Figure 1B, 3.3V/2.5V Output Load Test Circuit.



TABLE 4F. LVPECL DC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$, $V_{DDX} = 2.5V \pm 5\%$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
I_{IH}	Input High Current	PCLK	$V_{DD} = V_{IN} = 3.465V$		150	μA
		nPCLK	$V_{DD} = V_{IN} = 3.465V$		5	μA
I_{IL}	Input Low Current	PCLK	$V_{DD} = 3.465V, V_{IN} = 0V$	-5		μA
		nPCLK	$V_{DD} = 3.465V, V_{IN} = 0V$	-150		μA
V_{PP}	Peak-to-Peak Input Voltage		0.3		1	V
V_{CMR}	Common Mode Input Voltage; NOTE 1, 2		GND + 1.5		V_{DD}	V

NOTE 1: Common mode voltage is defined as V_{IH} .

NOTE 2: For single ended applications, the maximum input voltage for PCLK and nPCLK is $V_{DD} + 0.3V$.

TABLE 5B. AC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$, $V_{DDX} = 2.5V \pm 5\%$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{MAX}	Input Frequency				250	MHz
tp_{LH}	Propagation Delay, Low to High; NOTE 1	$f \leq 250MHz$		3.5		ns
tp_{HL}	Propagation Delay, High to Low; NOTE 1	$f \leq 250MHz$		3.5		ns
$tsk(b)$	Bank Skew; NOTE 2, 7	Measured on rising edge at $V_{DDX}/2$			100	ps
$tsk(o)$	Output Skew; NOTE 3, 7	Measured on rising edge at $V_{DDX}/2$			200	ps
$tsk(w)$	Multiple Frequency Skew; NOTE 4, 7	Measured on rising edge at $V_{DDX}/2$			350	ps
$tsk(pp)$	Part-to-Part Skew; NOTE 5, 7	Measured on rising edge at $V_{DDX}/2$		500		ps
t_R	Output Rise Time; NOTE 6	20% to 80%		700		ps
t_F	Output Fall Time; NOTE 6	20% to 80%		700		ps
odc	Output Duty Cycle			50		%
t_{EN}	Output Enable Time; NOTE 6	$f = 10MHz$				ns
t_{DIS}	Output Disable Time; NOTE 6	$f = 10MHz$				ns

All parameters measured at 250MHz unless noted otherwise.

NOTE 1: Measured from the $V_{DD}/2$ of the input to $V_{DDX}/2$ of the output.

NOTE 2: Defined as skew within a bank of outputs at the same supply voltages and with equal load conditions.

NOTE 3: Defined as skew across banks of outputs at the same supply voltages and with equal load conditions.

Measured at $V_{DDX}/2$.

NOTE 4: Defined as skew across banks of outputs operating at different frequencies with the same supply voltages and equal load conditions.

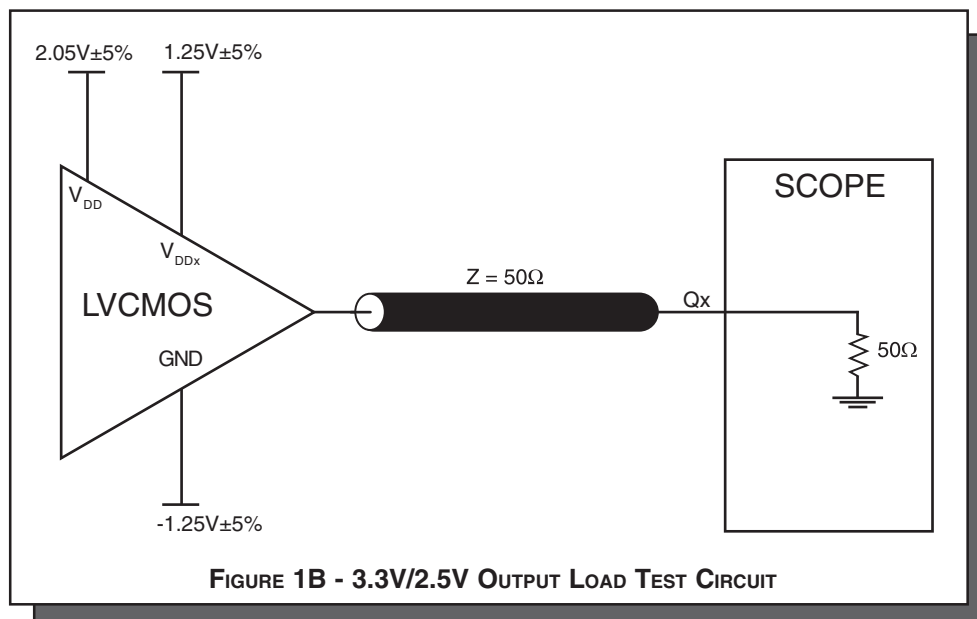
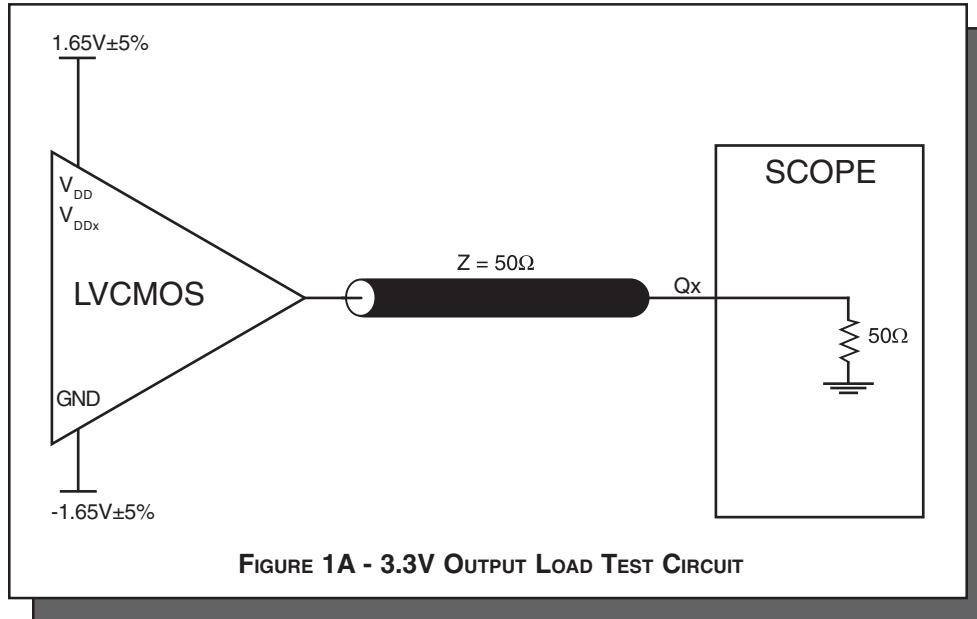
NOTE 5: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at $V_{DDX}/2$.

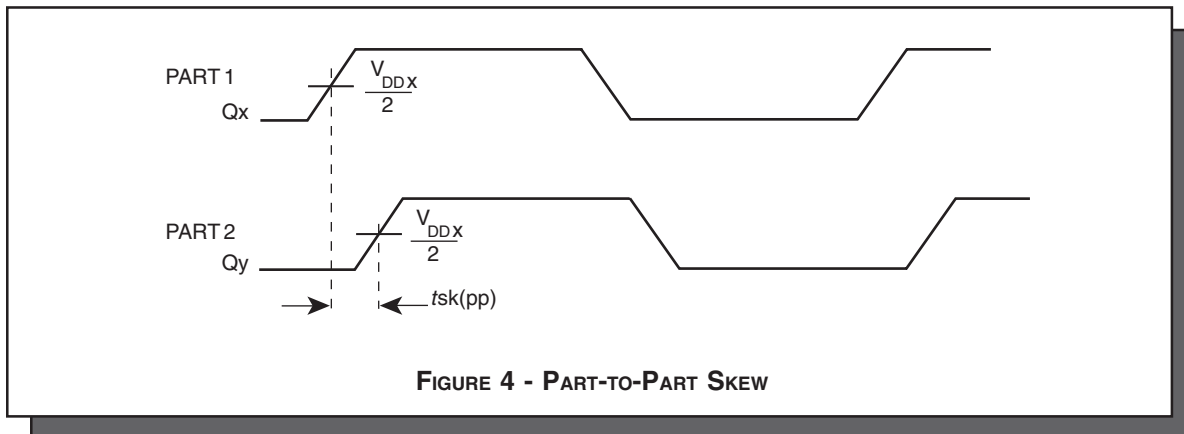
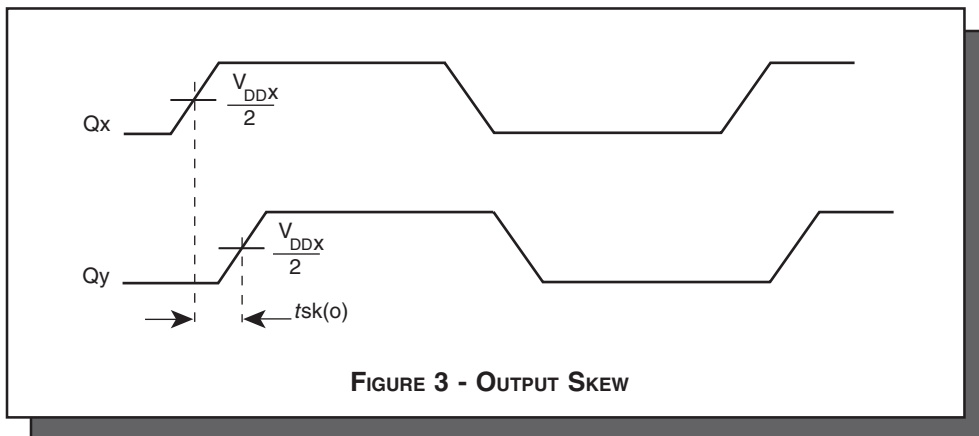
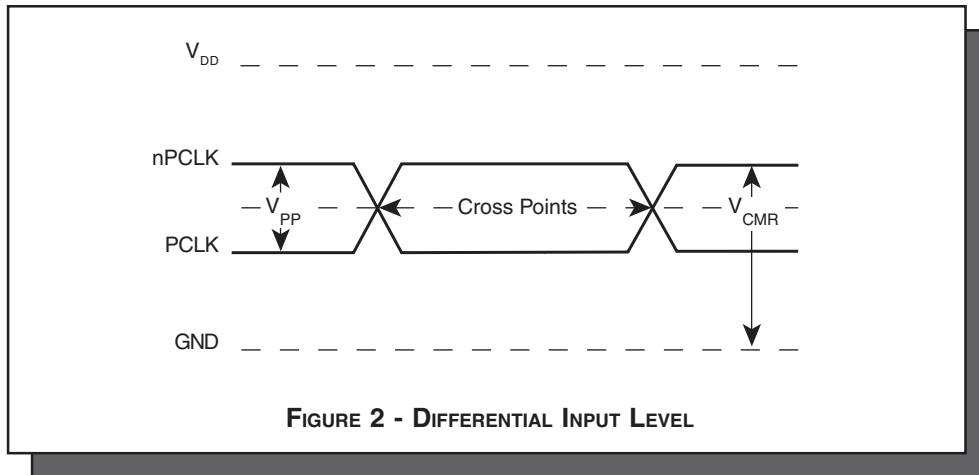
NOTE 6: These parameters are guaranteed by characterization. Not tested in production.

NOTE 7: This parameter is defined in accordance with JEDEC Standard 65.



PARAMETER MEASUREMENT INFORMATION





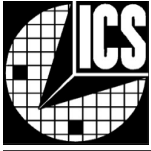


FIGURE 5 - INPUT AND OUTPUT RISE AND FALL TIME

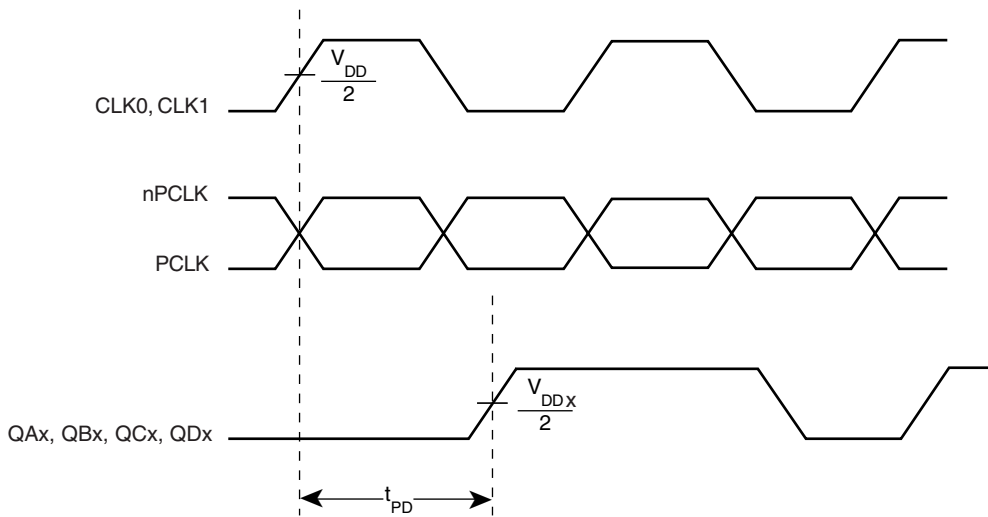
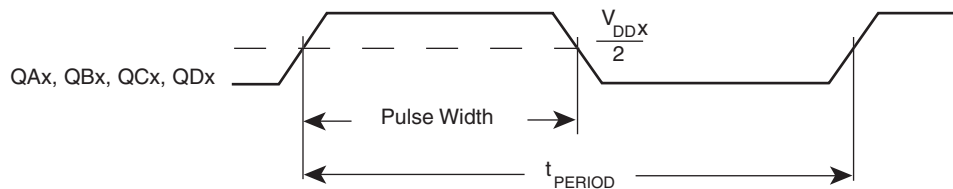


FIGURE 6 - PROPAGATION DELAY



$$odc = \frac{t_{PW}}{t_{PERIOD}}$$

FIGURE 7 - odc & t_{PERIOD}



RELIABILITY INFORMATION

TABLE 6. θ_{JA} vs. AIR FLOW TABLE

θ_{JA} by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

TRANSISTOR COUNT

The transistor count for ICS87949-01 is: 1545



PACKAGE OUTLINE - Y SUFFIX

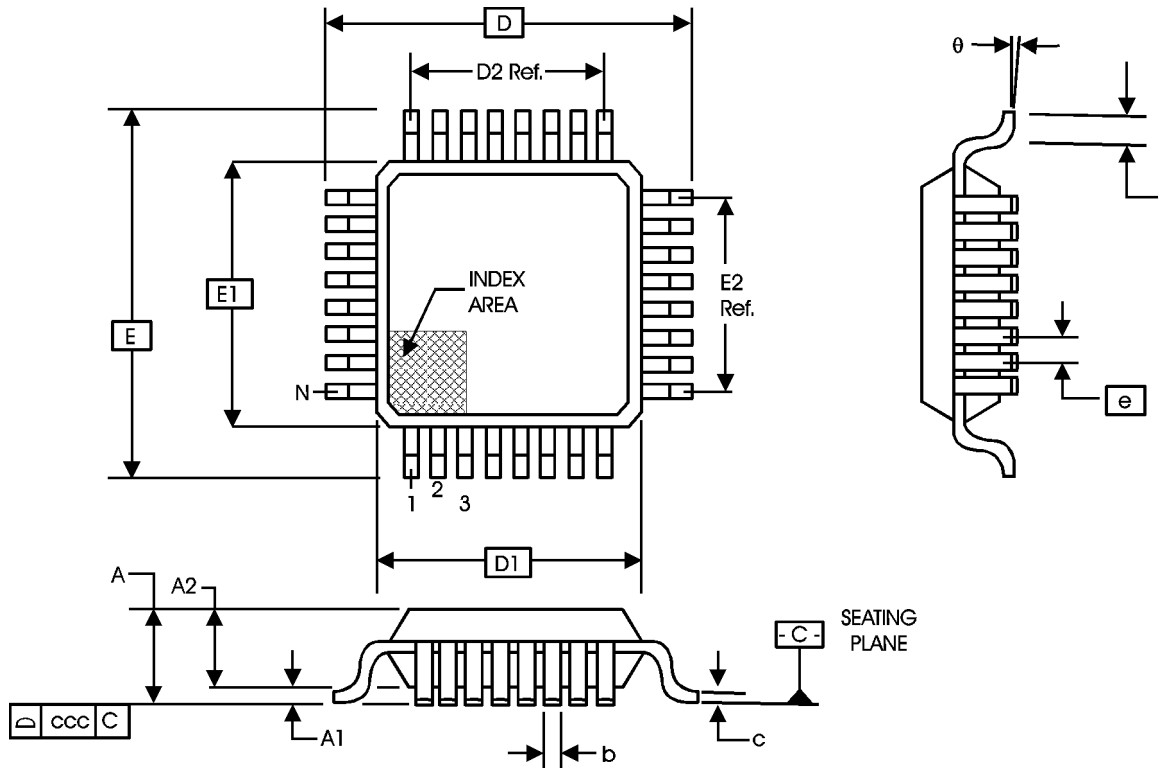


TABLE 7. PACKAGE DIMENSIONS

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS			
SYMBOL	BBC		
	MINIMUM	NOMINAL	MAXIMUM
N	48		
A	--	--	1.60
A1	0.05	--	0.15
A2	1.35	1.40	1.45
b	0.17	0.22	0.27
c	0.09	--	0.20
D	9.00 BASIC		
D1	7.00 BASIC		
D2	5.50 Ref.		
E	9.00 BASIC		
E1	7.00 BASIC		
E2	5.50 Ref.		
e	0.50 BASIC		
L	0.45	0.60	0.75
theta	0°	--	7°
ccc	--	--	0.08

Reference Document: JEDEC Publication 95, MS-026



Integrated
Circuit
Systems, Inc.

ICS87949-01
LOW SKEW $\div 1, \div 2$
CLOCK GENERATOR

TABLE 8. ORDERING INFORMATION

Part/Order Number	Marking	Package	Count	Temperature
ICS87949AY-01	ICS87949AY-01	48 Lead LQFP	250 per tray	0°C to 70°C
ICS87949AY-01T	ICS87949AY-01	48 Lead LQFP on Tape and Reel	1000	0°C to 70°C

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